

LM185/LM285/LM385 Adjustable Micropower Voltage References

Check for Samples: [LM185-ADJ](#), [LM285-ADJ](#), [LM385-ADJ](#)

FEATURES

- Adjustable from 1.24V to 5.30V
- Operating Current of 10 μ A to 20mA
- 1% and 2% Initial Tolerance
- 1 Ω Dynamic Impedance
- Low Temperature Coefficient

DESCRIPTION

The LM185/LM285/LM385 are micropower 3-terminal adjustable band-gap voltage reference diodes. Operating from 1.24 to 5.3V and over a 10 μ A to 20mA current range, they feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming is used to provide tight voltage tolerance. Since the LM185 band-gap reference uses only transistors and resistors, low noise and good long-term stability result.

Careful design of the LM185 has made the device tolerant of capacitive loading, making it easy to use in almost any reference application. The wide dynamic operating range allows its use with widely varying supplies with excellent regulation.

The extremely low power drain of the LM185 makes it useful for micropower circuitry. This voltage reference can be used to make portable meters, regulators or general purpose analog circuitry with battery life approaching shelf life. Further, the wide operating current allows it to replace older references with a tighter tolerance part.

The LM185 is rated for operation over a -55°C to 125°C temperature range, while the LM285 is rated -40°C to 85°C and the LM385 0°C to 70°C . The LM185 is available in a hermetic TO package and a LCCC package, while the LM285/LM385 are available in a low-cost TO-92 package, as well as SOIC.

Connection Diagram

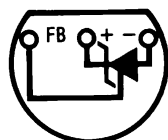


Figure 1. TO-92 Package Bottom View

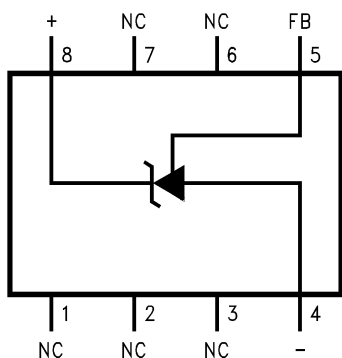


Figure 3. SOIC Package Top View

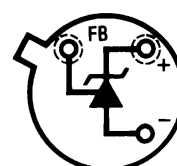


Figure 2. TO Package Bottom View

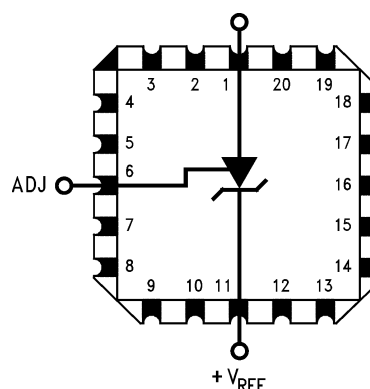


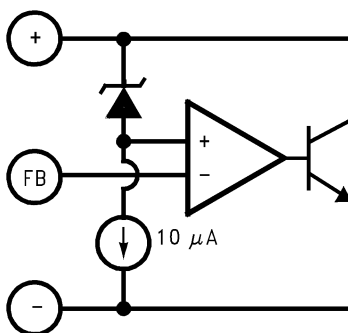
Figure 4. 20-LCCC Package Top View



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Block Diagram



Typical Applications

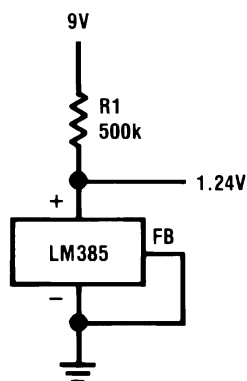
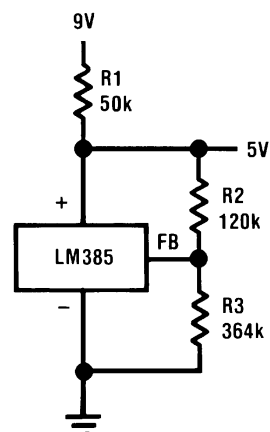


Figure 5. 1.2V Reference



$$V_{OUT} = 1.24 \left(\frac{R3}{R2} + 1 \right)$$

Figure 6. 5.0V Reference



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾⁽²⁾⁽³⁾

Reverse Current	30mA
Forward Current	10mA
Operating Temperature Range ⁽⁴⁾	
LM185 Series	–55°C to 125°C
LM285 Series	–40°C to 85°C
LM385 Series	0°C to 70°C
ESD Susceptibility ⁽⁵⁾	2kV
Storage Temperature	–55°C to 150°C
Soldering Information	
TO-92 Package (10 sec.)	260°C
TO Package (10 sec.)	300°C
SOIC Package	
Vapor Phase (60 sec.)	215°C
Infrared (15 sec.)	220°C
See An-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.	

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional. For specifications and test conditions, see the Electrical Characteristics. The specifications apply only for the test conditions listed.
- (2) Refer to RETS185H for military specifications.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (4) For elevated temperature operation, see [Table 1](#) and [Thermal Characteristics](#).
- (5) The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin.

Table 1. $T_{J(max)}$ for Elevated Temperature Operation

DEVICE	$T_{J(max)}$ (°C)
LM185	150
LM285	125
LM385	100

Thermal Characteristics

Over operating free-air temperature range (unless otherwise noted)

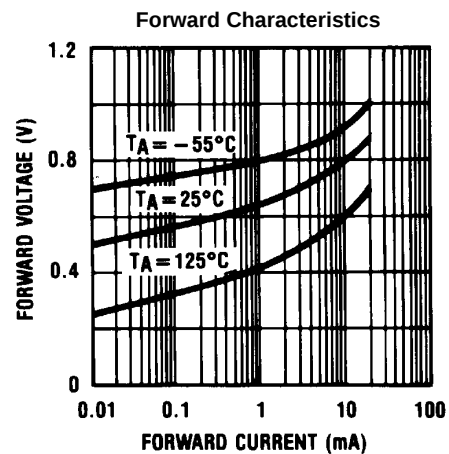
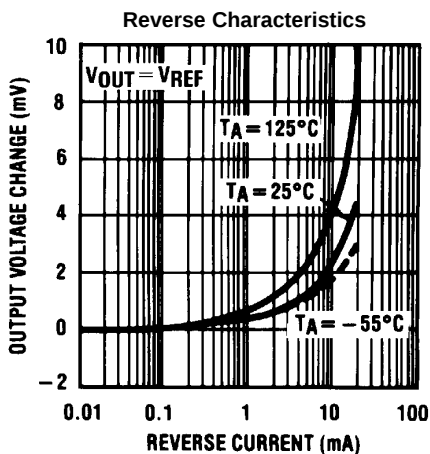
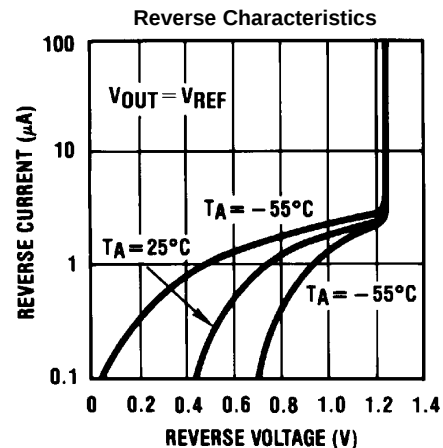
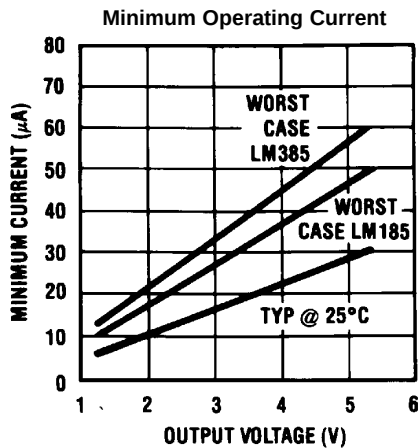
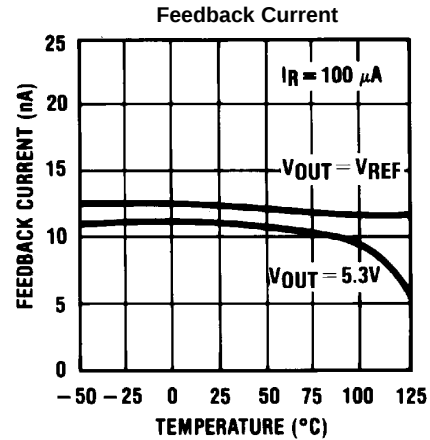
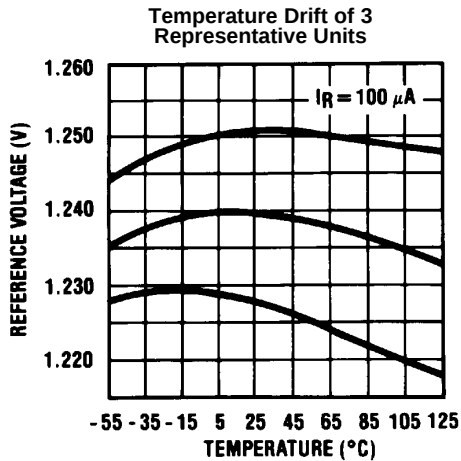
Thermal Resistance	TO-92	TO-46	SOIC
θ_{JA} (Junction to Ambient)	180°C/W (0.4" leads)	440°C/W	165°C/W
	170°C/W (0.125" leads)		
θ_{JC} (Junction to Case)	N/A	80°C/W	N/A

Electrical Characteristics⁽¹⁾

Parameter	Conditions		LM185, LM285					LM385				Units (Limit)	
			Typ	LM185BX, LM185BY LM185B, LM285BX, LM285BY		LM285		Typ	LM385BX, LM385BY		LM385		
				Tested Limit (2)	Design Limit (3)	Tested Limit (2)	Design Limit (3)		Tested Limit (2)	Design Limit (3)	Tested Limit (2)		Design Limit (3)
Reference Voltage	I _R = 100μA		1.240	1.252 1.255 1.228 1.215		1.265 1.215 1.205		1.240	1.252 1.228 1.215	1.255 1.215	1.265 1.215 1.205	V (max) V (min)	
Reference Voltage Change with Current	I _{MIN} < I _R < 1mA 1mA < I _R < 20mA		0.2 4	1 10	1.5 20	1 10	1.5 20	0.2 5	1 15	1.5 25	1 15	1.5 25 mV (max)	
Dynamic Output Impedance	I _R = 100μA, I _{AC} = 0.1 I _R	f = 100Hz V _{OUT} = V _{REF} V _{OUT} = 5.3V	 0.3 0.7					 0.4 1				 Ω	
Reference Voltage Change with Output Voltage	I _R = 100μA		 1	 3	 6	 3	 6	 2	 5	 10	 5	 10 mV (max)	
Feedback Current			13	20	25	20	25	16	30	35	30	35 nA (max)	
Minimum Operating Current (see curve)	V _{OUT} = V _{REF} V _{OUT} = 5.3V		6 30	9 45	10 50	9 45	10 50	7 35	11 55	13 60	11 55	13 60 μA (max)	
Output Wideband Noise	I _R = 100μA, 10Hz < f < 10kHz V _{OUT} = V _{REF} V _{OUT} = 5.3V		 50 170					 50 170				 μV _{rms}	
Average Temperature Coefficient (4)	I _R = 100μA	X Suffix Y Suffix All Others		30 50 150			150		30 50 150		 150	 ppm/°C (max)	
Long Term Stability	I _R = 100μA, T = 1000 Hr, T _A = 25°C ± 0.1°C		20					20				ppm	

- (1) Parameters identified with **boldface type** apply at temperature extremes. All other numbers apply at $T_A = T_J = 25^{\circ}C$. Unless otherwise specified, all parameters apply for $V_{REF} < V_{OUT} < 5.3V$.
- (2) Production tested.
- (3) Not production tested. These limits are not to be used to calculate average outgoing quality levels.
- (4) The average temperature coefficient is defined as the maximum deviation of reference voltage at all measured temperatures from T_{MIN} to T_{MAX} , divided by $T_{MAX} - T_{MIN}$. The measured temperatures are $-55, -40, 0, 25, 70, 85, 125^{\circ}C$.

Typical Performance Characteristics



Typical Performance Characteristics (continued)

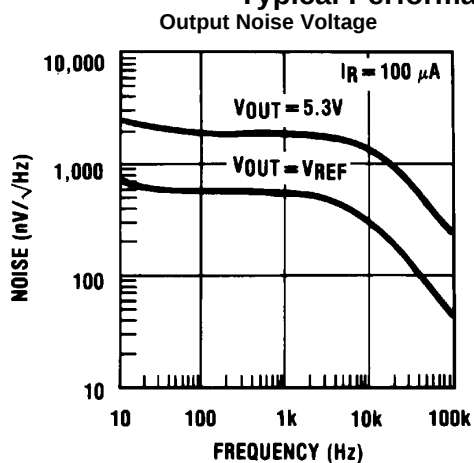


Figure 13.

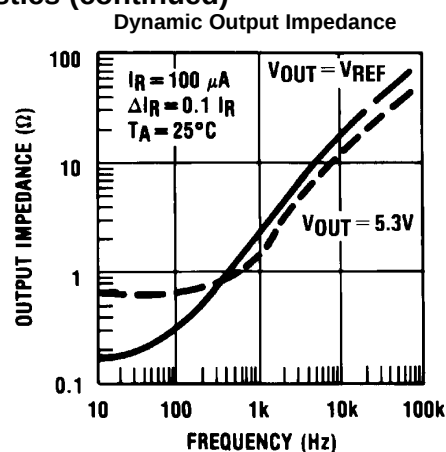


Figure 14.

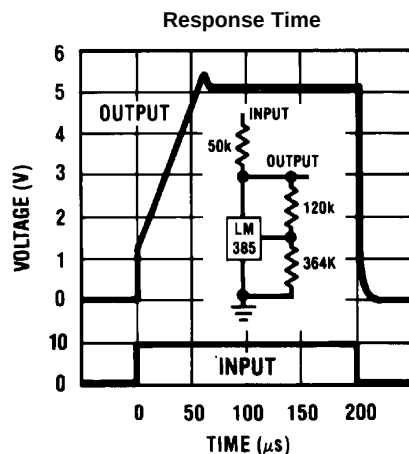


Figure 15.

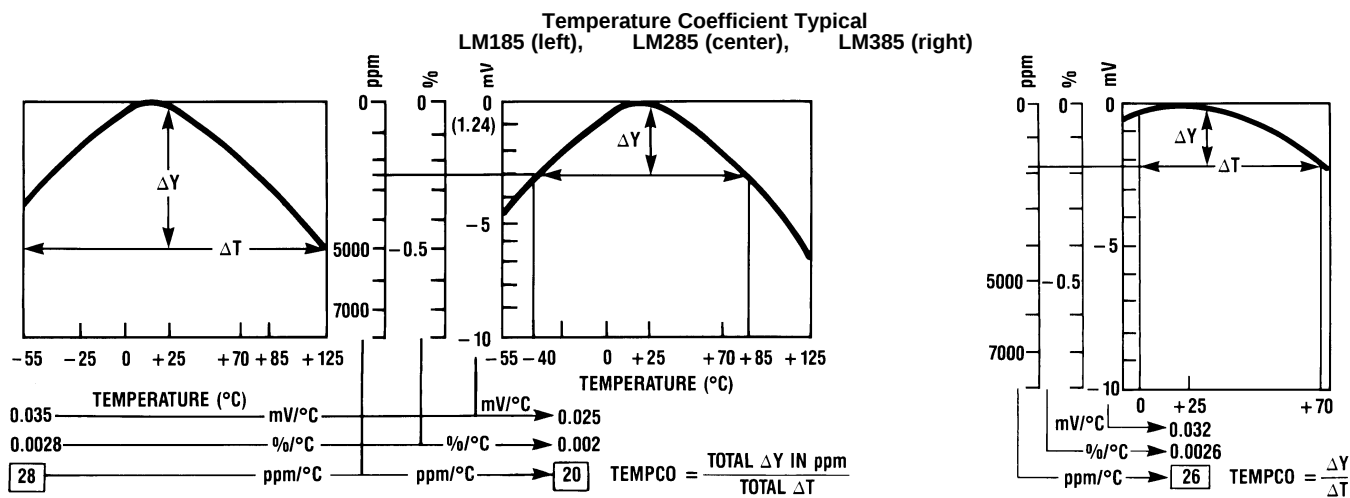


Figure 16.

TYPICAL APPLICATIONS

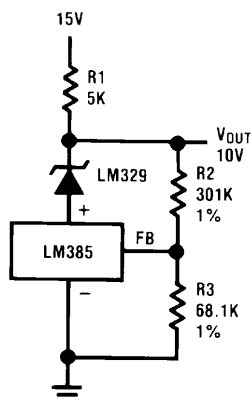


Figure 17. Precision 10V Reference

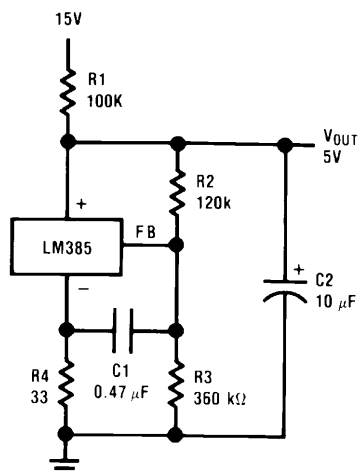


Figure 18. Low AC Noise Reference

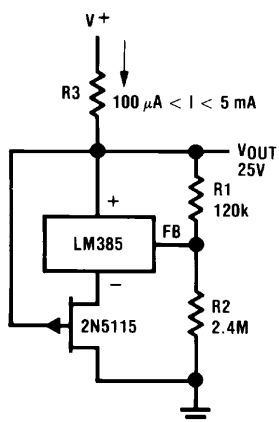


Figure 19. 25V Low Current Shunt Regulator

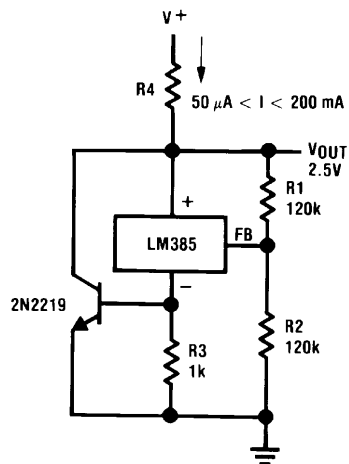


Figure 20. 200 mA Shunt Regulator

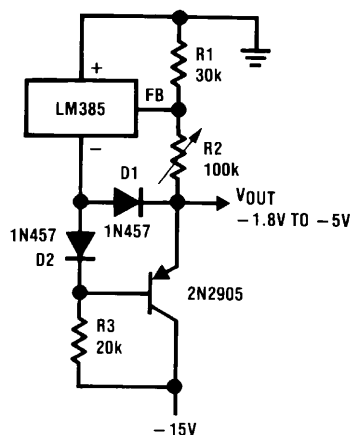


Figure 21. Series-Shunt 20 mA Regulator

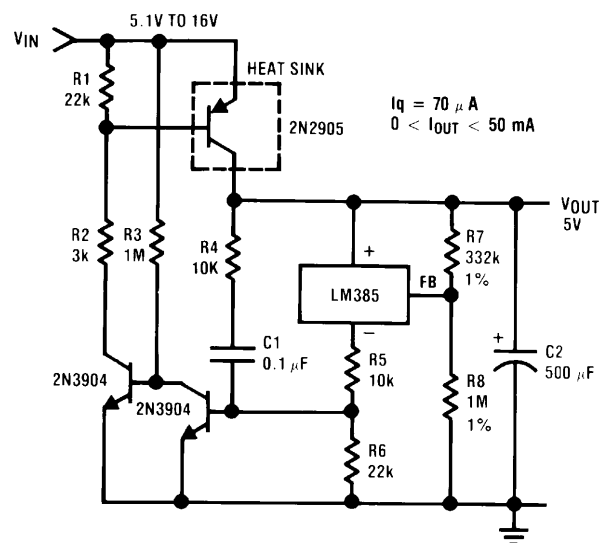


Figure 22. High Efficiency Low Power Regulator

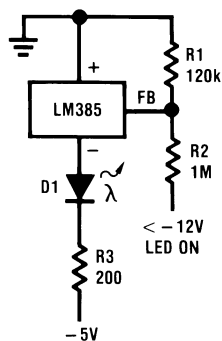


Figure 23. Voltage Level Detector

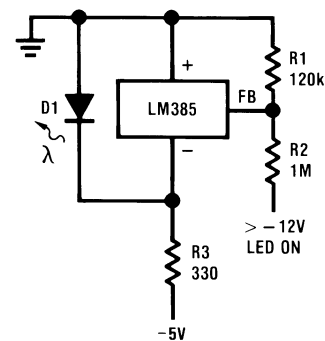
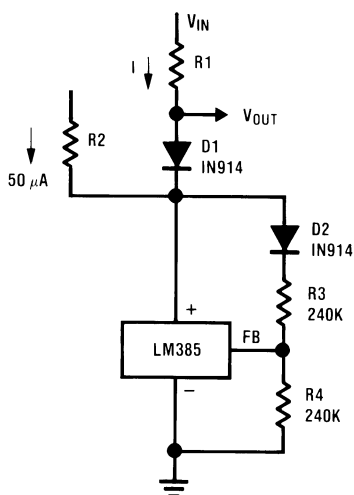
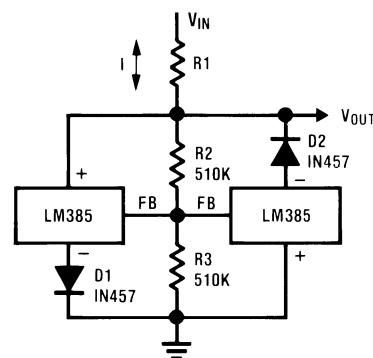


Figure 24. Voltage Level Detector

Figure 25. Fast Positive Clamp
 $2.4V + \Delta V_{D1}$ Figure 26. Bidirectional Clamp
 $\pm 2.4V$

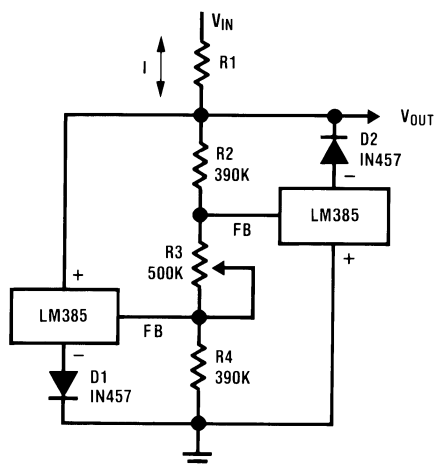


Figure 27. Bidirectional Adjustable Clamp
 $\pm 1.8\text{V}$ to $\pm 2.4\text{V}$

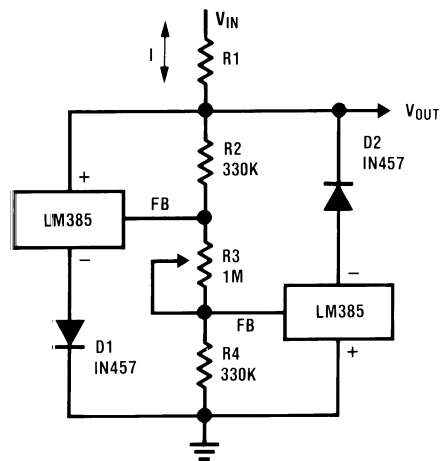


Figure 28. Bidirectional Adjustable Clamp
 $\pm 2.4\text{V}$ to $\pm 6\text{V}$

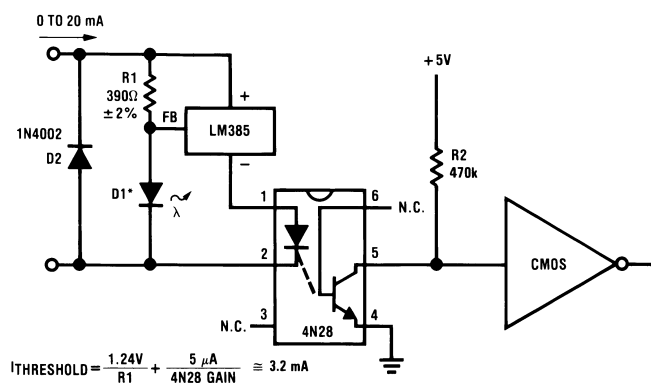


Figure 29. Simple Floating Current Detector

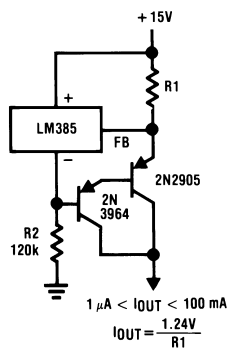
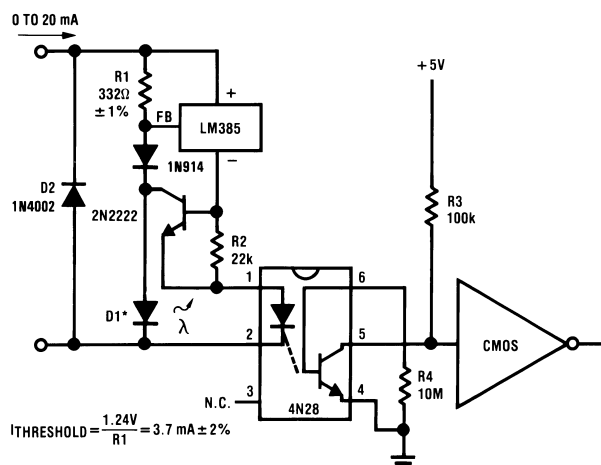


Figure 30. Current Source



*D1 can be any LED, $V_F=1.5\text{V to } 2.2\text{V}$ at 3 mA . D1 may act as an indicator. D1 will be on if $I_{\text{THRESHOLD}}$ falls below the threshold current, except with $I=0$.

Figure 31. Precision Floating Current Detector

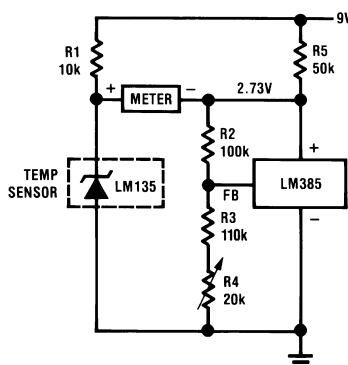


Figure 32. Centigrade Thermometer, 10mV/°C

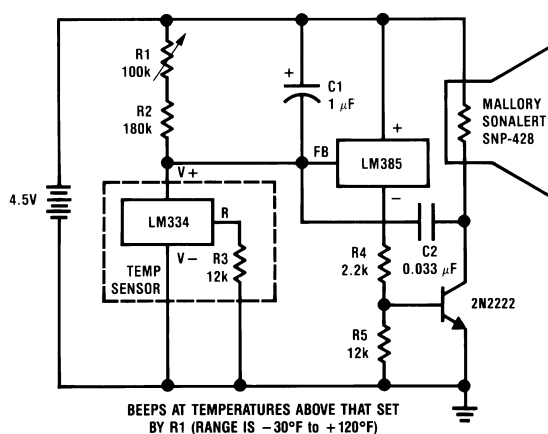
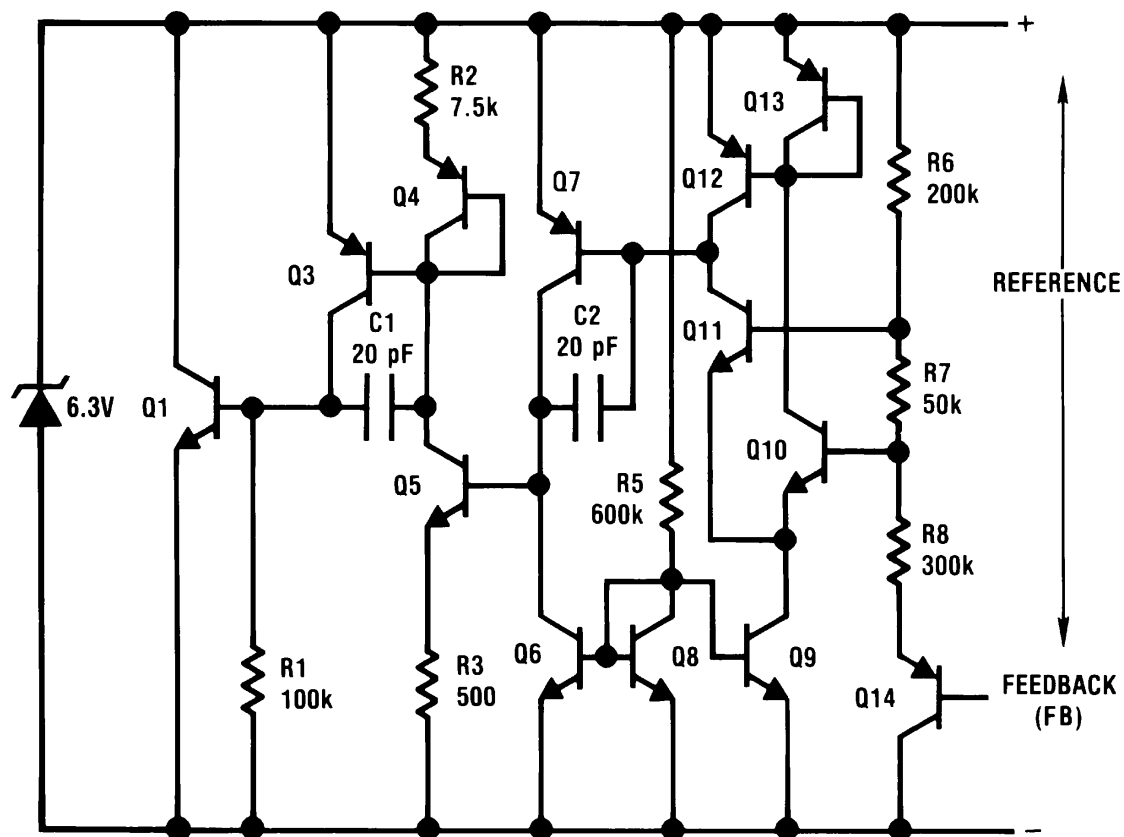


Figure 33. Freezer Alarm

Schematic Diagram



REVISION HISTORY

Changes from Revision E (April 2013) to Revision F	Page
• Changed layout of National Data Sheet to TI format	11

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM185BH	Active	Production	TO (NDV) 3	1000 BULK	No	Call TI	Call TI	-55 to 125	(LM185BH, LM185BH)
LM185BH/NOPB	Active	Production	TO (NDV) 3	1000 BULK	Yes	Call TI	Level-1-NA-UNLIM	-55 to 125	(LM185BH, LM185BH)
LM285BXZ/NOPB	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	-40 to 85	LM285 BXZ
LM285BXZ/NOPB.B	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	-40 to 85	LM285 BXZ
LM285BYM/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 BYM
LM285BYM/NOPB.B	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 BYM
LM285BYMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 BYM
LM285BYMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 BYM
LM285BYZ/NOPB	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	-40 to 85	LM285 BYZ
LM285BYZ/NOPB.B	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	-40 to 85	LM285 BYZ
LM285M/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 M
LM285M/NOPB.B	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 M
LM285MX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 M
LM285MX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	LM285 M
LM285Z/NOPB	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	-40 to 85	LM285 Z
LM285Z/NOPB.B	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	-40 to 85	LM285 Z

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM385BM/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 BM
LM385BM/NOPB.B	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 BM
LM385BMX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 BM
LM385BMX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 BM
LM385BXZ/NOPB	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 BXZ
LM385BXZ/NOPB.B	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 BXZ
LM385BYZ/NOPB	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 BYZ
LM385BYZ/NOPB.B	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 BYZ
LM385BZ/NOPB	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 BZ
LM385BZ/NOPB.B	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 BZ
LM385M/NOPB	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 M
LM385M/NOPB.B	Active	Production	SOIC (D) 8	95 TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 M
LM385MX/NOPB	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 M
LM385MX/NOPB.B	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LM385 M
LM385Z/NOPB	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 Z
LM385Z/NOPB.B	Active	Production	TO-92 (LP) 3	1800 BULK	Yes	Call TI	N/A for Pkg Type	0 to 70	LM385 Z

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM285BYMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM285MX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385MX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

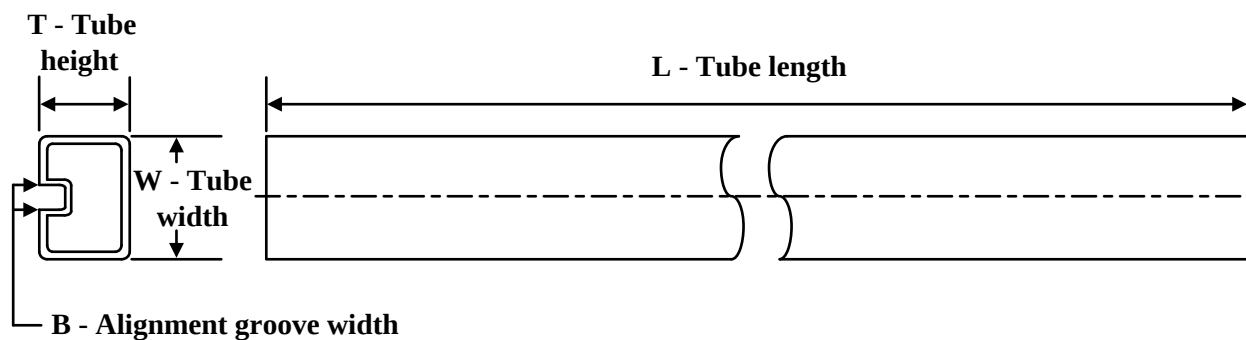
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM285BYMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM285MX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385MX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
LM285BYM/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM285BYM/NOPB.B	D	SOIC	8	95	495	8	4064	3.05
LM285M/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM285M/NOPB.B	D	SOIC	8	95	495	8	4064	3.05
LM385BM/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM385BM/NOPB.B	D	SOIC	8	95	495	8	4064	3.05
LM385M/NOPB	D	SOIC	8	95	495	8	4064	3.05
LM385M/NOPB.B	D	SOIC	8	95	495	8	4064	3.05

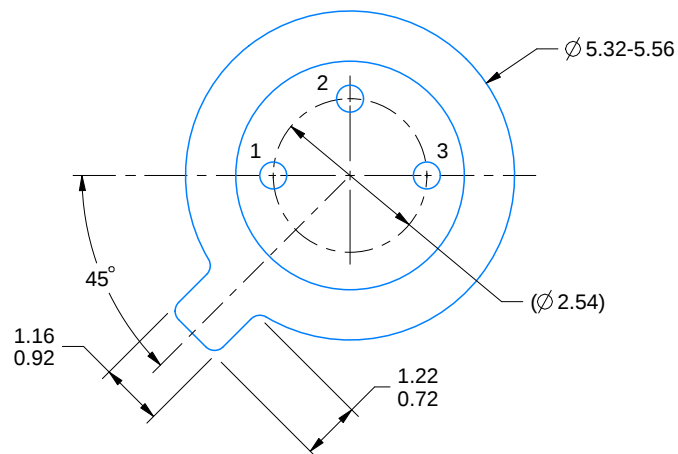
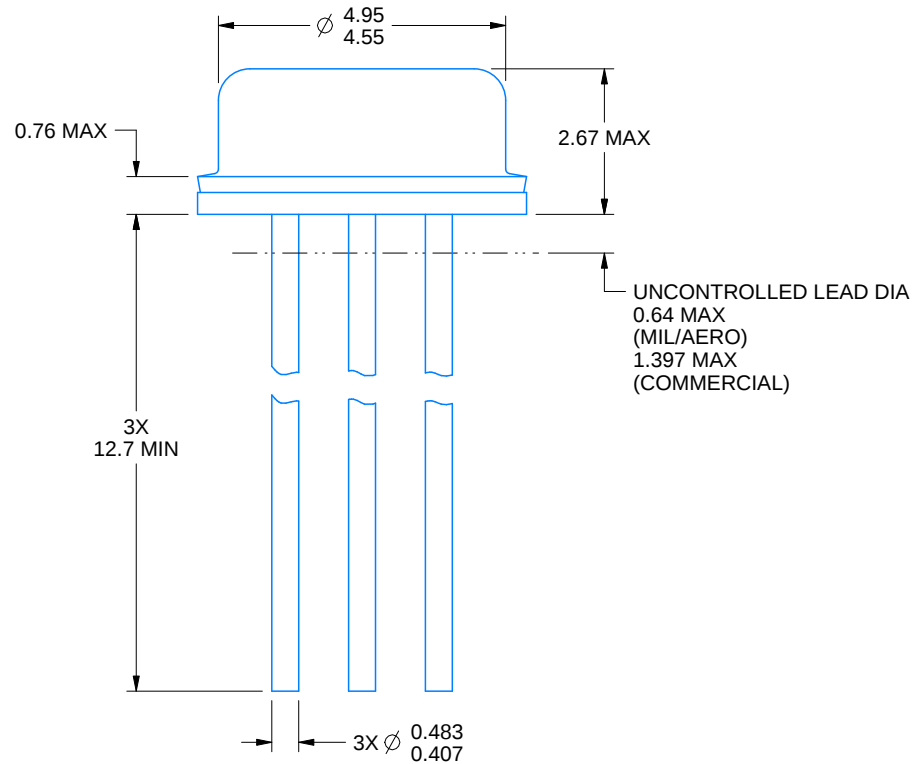
NDV0003H



PACKAGE OUTLINE

TO-CAN - 2.67 mm max height

TRANSISTOR OUTLINE



4219876/B 09/2024

NOTES:

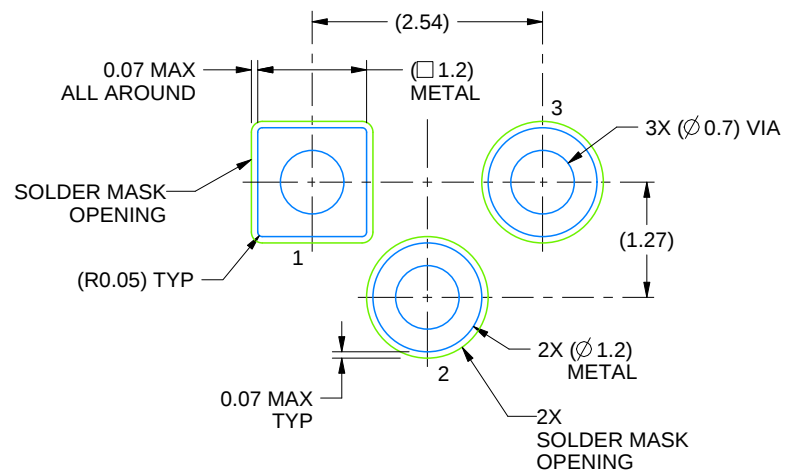
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-46.

EXAMPLE BOARD LAYOUT

NDV0003H

TO-CAN - 2.67 mm max height

TRANSISTOR OUTLINE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:12X

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PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

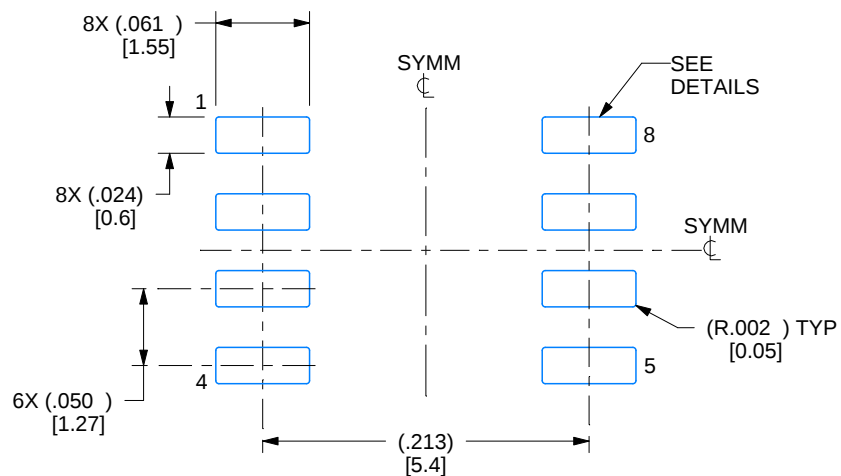


1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



TO-92 - 5.34 mm max height

Technical drawing of a connector assembly showing three views: a side view on the left, a top view in the center, and a partial side view on the right.

Side View (Left):

- Body width: $2 \times 4 \text{ MAX}$
- Pin width: $2 \times \frac{2.9}{2.4}$
- Seating Plane

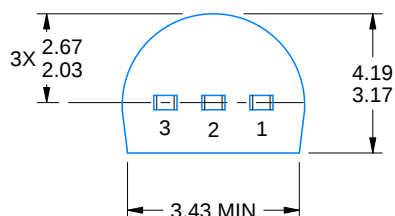
Top View (Center):

- Body width: $5.21 / 4.44$
- Body height: $5.34 / 4.32$
- Pin pitch: $(2.54) \text{ NOTE 3}$
- Pin width: $(1.5) \text{ TYP}$
- Pin thickness: $(0.51) \text{ TYP}$
- Pin length: $6 \times 0.076 \text{ MAX}$
- Pin length (total): $3 \times 12.7 \text{ MIN}$
- Pin width: $3 \times \frac{0.55}{0.38}$
- Pin spacing: $2 \times 1.27 \pm 0.13$
- Seating Plane
- EJECTOR PIN OPTIONAL

Partial Side View (Right):

- Pin width: $3 \times \frac{0.43}{0.35}$

STRAIGHT LEAD OPTION



NOTES:

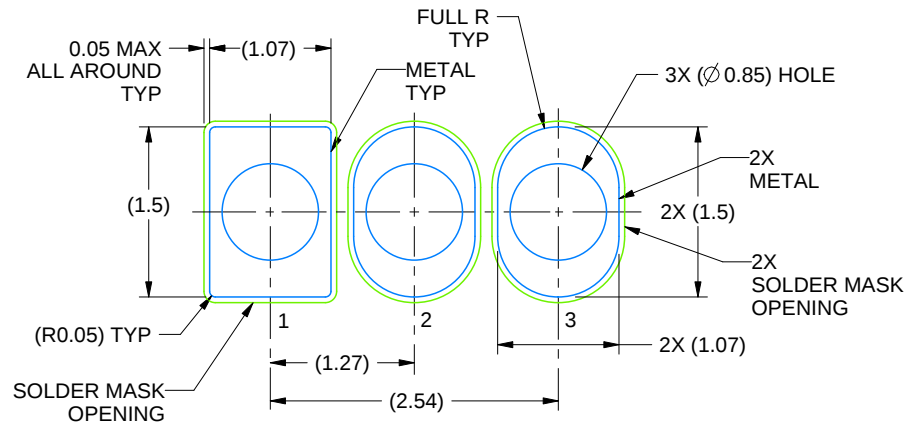
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
 - a. Straight lead option available in bulk pack only.
 - b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.

EXAMPLE BOARD LAYOUT

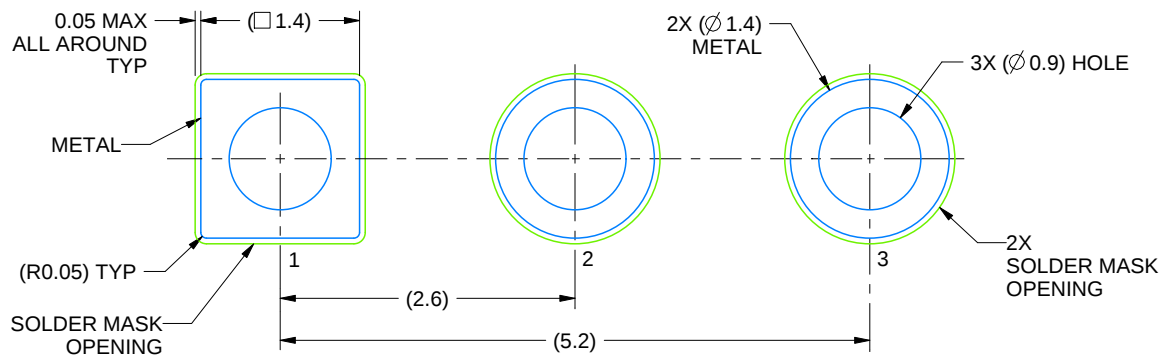
LP0003A

TO-92 - 5.34 mm max height

TO-92



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

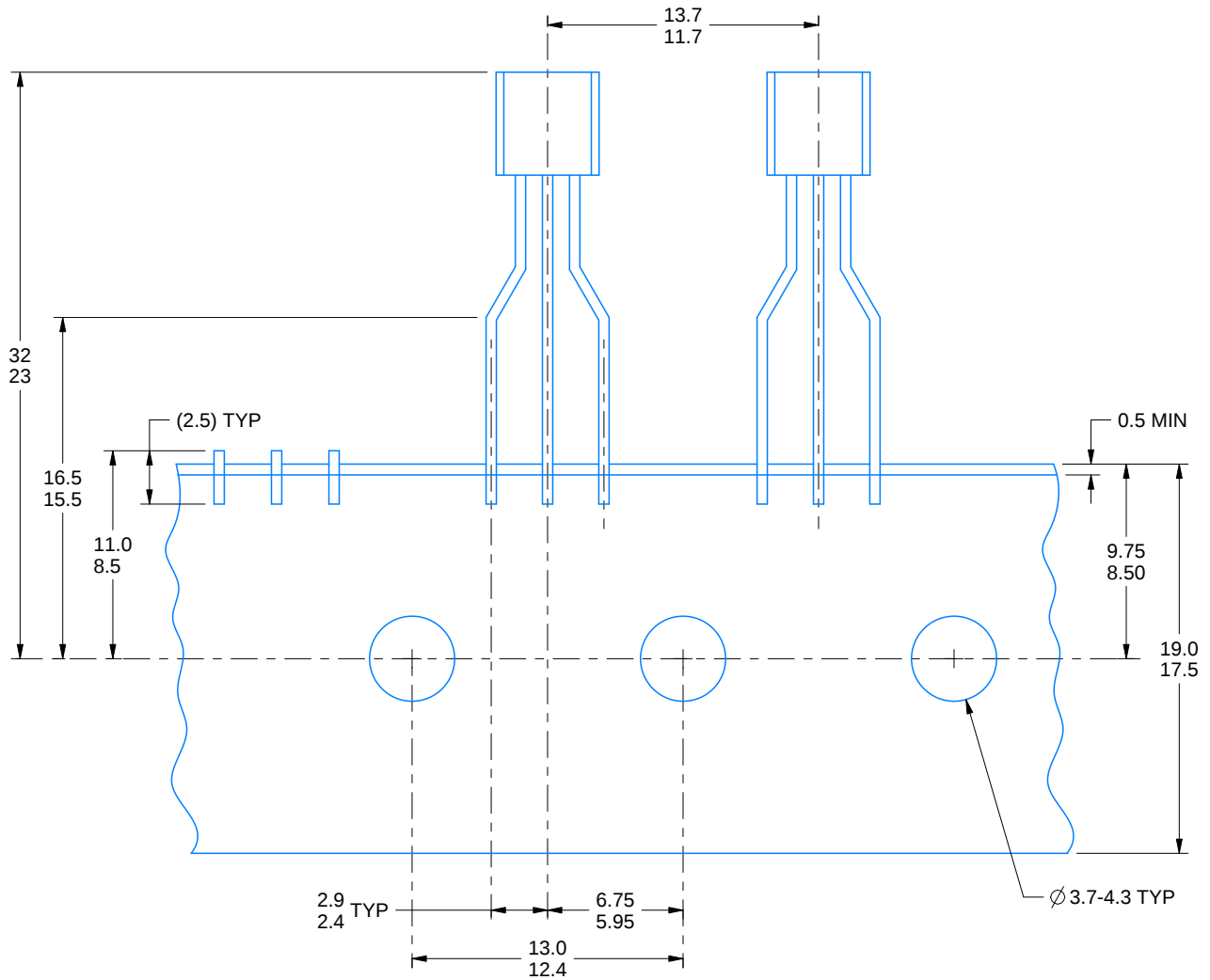
4215214/C 04/2025

TAPE SPECIFICATIONS

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/C 04/2025

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